

## Scholarship History

The BUILD Scholarship Program is generously supported by the Abbey Scholarship Program and the Heilman Scholarship Fund to benefit BUILD participants in their educational pursuits.

The Abbey Family envisioned a fund to give youth the opportunity to pursue their dreams of post-secondary education and to bring the “mainstream dream” of college and career within the reach of BUILD participants. The Abbey Scholarship Program provides scholarships that give access to education and career opportunities that have traditionally not been available to highly at-risk youth in BUILD’s target communities. The minimum scholarship granted will be \$2,500; the maximum annual scholarship will be \$10,000.

The Heilman Scholarship Fund was established in memory of Eleanor and John Heilman by their children, grandchildren and other generous donors, to give youth at BUILD an opportunity to pursue their dreams of education and career-training. As a Juvenile Court Justice in Dutchess County, New York, Judge Heilman worked to ensure that all youth were treated fairly and given the opportunity to succeed. As an ensign in the Navy Nurse Corps during World War II, and later a volunteer in community youth organizations, Mrs. Heilman worked to enhance the quality of life for people of all ages. Together for 60 years, Eleanor and John Heilman committed their lives to improving the lives of others. The Heilman Fund serves to bridge the gap between grants, loans and scholarships by providing the “final dollars that are needed for recipients to enroll and participate in accredited secondary schools, academic enrichment programs, and colleges. The minimum scholarship granted will be \$1.00 and the maximum annual scholarship from the Heilman Fund will be \$2,500.

## Eligibility Guidelines

- Be a high school senior during the 2019-20 academic school year, or already have a high school diploma or GED.
- Be in “good standing with the law (e.g., if on probation/parole, be in compliance with requirements; not commit another infraction; and not return to detention or incarceration.
- Have participated in BUILD youth programs within the past 6 months, or be alumni of BUILD and have been in contact with BUILD staff.
- Be accepted by, or currently enrolled in:
  - An accredited independent secondary school (e.g. private or parochial high school); or
  - An accredited two-year or four-year college or university
  - An accredited vocational/trade school
- Have maintained a minimum 2.0 on a 4.0 scale, or a “C” average in the preceding and current year of education.
- Be recommended by a BUILD staff member.
- Have worked with BUILD staff and/or some other resource, applied for appropriate scholarships and loans, and have received responses to those applications.
- Be in need of additional funds in order to attend a post-secondary institution.
- Be available for a 1-on-1 interview with the scholarship committee at an undisclosed date/time.

## Instructions

In order to fill out this application, please follow these instructions:

1. BUILD Applications are due in its completion by 11:59 pm CDT on **Sunday, July 4, 2021.**
2. Applications can be filled out and sent via e-mail to [scholarships@buildchicago.org](mailto:scholarships@buildchicago.org). Click on the link posted on <http://www.buildchicago.org/education-corner> to complete the editable application.
3. **Save your scholarship application to your computer hard drive before beginning and re-open.** The form will not be savable if typed on before being saved. No electronic signatures will be accepted for final submission. Physical Signatures ONLY.
4. Printed applications should be returned directly to Ashley Dale, College Access and Persistence Coordinator.
5. All questions must be answered completely on all pages. Any applications with missing information and documentation will not be considered.

Please complete and submit **ALL** materials to:

[scholarships@buildchicago.org](mailto:scholarships@buildchicago.org)

For more information call: 773-227-2880, visit [www.buildchicago.org](http://www.buildchicago.org)

or e-mail [ashleydale@buildchicago.org](mailto:ashleydale@buildchicago.org)

# Application Checklist

Name \_\_\_\_\_

Date \_\_\_\_\_

I have:

- Answered all questions on the application form and profile sheet completely and included my signature.
- Included the BUILD Staff Member Recommendation.
- Included the Recommendation Form from a teacher, principal and/or an academic counselor.
- Submitted a personal essay that is grammatically correct, clear, authentic, and compelling.
- Submitted evidence of financial need (financial aid award letter or bill from the school) and documentation of other scholarships and financial aid I have pursued.
- Included most up-to-date copy of my transcript and current grades.

Previous Applicants only:

- Submitted my receipts and list of expenditures to the BUILD office.
- Submitted grade report from the most recent semester/trimester/quarter to the BUILD office.
- Submitted a personal essay that is grammatically correct, clear, authentic, and compelling.
- Submitted letter(s) verifying my community service activities to BUILD.
- Contacted an Education Outreach Specialist at BUILD during each semester/trimester/quarter for which I received funds.

**My signature indicates that all information is complete, factual and honestly presented.**

Signature \_\_\_\_\_

Date \_\_\_\_\_

**NOTE: Applicants without all of the required documentation will not be considered. If you have any questions or required assistance, please e-mail [scholarships@buildchicago.org](mailto:scholarships@buildchicago.org) .**



## BUILD Inc. Scholarship Application Form 2021

*Due: Sunday July 4, 2021*

Applicant's Name: \_\_\_\_\_

Social Security #: \_\_\_\_\_ Birthdate: \_\_\_\_\_ Age: \_\_\_\_\_

Home/Mailing Address: \_\_\_\_\_ Apt #: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ Zip Code: \_\_\_\_\_

Home Phone #: \_\_\_\_\_ Cell Phone #: \_\_\_\_\_

E-mail Address: \_\_\_\_\_

Name of current educational institution: \_\_\_\_\_

School Address: \_\_\_\_\_ Grade: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ Zip Code: \_\_\_\_\_

Expected Graduation Date: \_\_\_\_\_ GPA: \_\_\_\_\_ Class Rank: \_\_\_\_\_ / \_\_\_\_\_

Name of secondary or post-secondary institution you will be attending:

\_\_\_\_\_

Intended major/area of interest: \_\_\_\_\_

Are you the first in your family to attend college? \_\_\_\_\_ Expected Graduation Date: \_\_\_\_\_

In a brief statement, explain how much funding you are requesting and what you expect it to cover:

\_\_\_\_\_

\_\_\_\_\_

\_\_\_\_\_

\_\_\_\_\_

## Essay Questions

On a separate page, answer the following questions in 100-200 words. A personal essay that is grammatically correct, clear, authentic, and compelling. **Answers must be typed.**

### **New Applicants:**

1. What difference will this scholarship make in your life?
2. If you receive a BUILD scholarship that does not cover all of the costs shown on the school bill, how will you cover the remaining balance?
3. Identify the tools and support you will seek to help you successfully navigate through your academic career?

### **Previous Applicants:**

1. What have you learned about yourself from your college experience thus far? Have your personal and/or professional goals changed at all due to your college experience?
2. How has the scholarship helped you achieve your educational goals?
3. If you receive a BUILD scholarship that does not cover all of the costs shown on the school bill, how will you cover the remaining balance?

## Statement of Commitment

If awarded a BUILD scholarship, I \_\_\_\_\_ understand I am expected to make a minimum of two contacts per semester/quarter/trimester to the College Access and Persistence Coordinator to discuss my academic progress and any challenges encountered during my academic endeavors. I will provide my mid-term and final grades for review for each semester/quarter/trimester. Additionally, I agree to join BUILD's College Network and participate in BUILD activities when possible.

Signature:

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Date:

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## BUILD Staff Recommendation

Submit this form to a BUILD staff member with whom you have worked closely. When the staff member has completed the form, he or she should scan and e-mail it to the College Access and Persistence Coordinator.

Applicant's Name: \_\_\_\_\_

Staff Name/Title: \_\_\_\_\_

How long have you known this participant? \_\_\_\_\_

In what capacity have you known this participant?  
\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

**Please rate the participant by circling the corresponding description for each category:**

<b>Overcoming hardship</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Concern for others</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Leadership</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Need</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>

Please use this form, or attach another sheet, to add any explanation of your ratings or other comments that you fee may be useful in evaluating the application.

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

Signature and Title

Date

Thank you for your time. Please e-mail this form to: [scholarships@buildchicago.org](mailto:scholarships@buildchicago.org)

Subject Line: Staff Recommendation for first and last name of youth.

**Due in completion by 11:59 p.m. CDT on Sunday, July 4, 2021**

## Teacher/Principal/Counselor Recommendation Brag Sheet

Applicants- Complete the information below and submit this form to a teacher, principal or academic counselor with whom you have worked closely, to help them complete the Recommendation Form. This form should not be submitted as part of your application.

Applicant's Name: \_\_\_\_\_

Current School: \_\_\_\_\_

My BUILD Participation?

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Remember when... (a time I showed strength of character or concern for others)

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Why I want to go to college:

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## Teacher/Professor/Principal/Counselor Recommendation

Submit this form to a teacher or professor, principal or academic counselor with whom you have worked closely. He or she may send the completed form to [scholarships@buildchicago.org](mailto:scholarships@buildchicago.org).

Name/Title: \_\_\_\_\_

Applicant's Name: \_\_\_\_\_

How long have you known this participant? \_\_\_\_\_

In what capacity have you known this participant?

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

**Please rate the participant by circling the corresponding description for each category:**

<b>Overcoming hardship</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Concern for others</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Leadership</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>
<b>Need</b>	<b>Superior</b>	<b>Above average</b>	<b>Below average</b>	<b>Poor</b>

Please use this form, or attach another sheet, to add any explanation of your ratings or other comments that you feel may be useful in evaluating the application.

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

\_\_\_\_\_  
Signature and Title

\_\_\_\_\_  
Date

Thank you for your time. Please e-mail to:

[scholarships@buildchicago.org](mailto:scholarships@buildchicago.org)

**Due in completion by 11:59 p.m. CDT on Sunday, July 4, 2021**